



DF005 THRU DF10

GLASS PASSIVATED CHIP SINGLE-PHASE BRIDGE RECTIFIER

Reverse Voltage - 50 to 1000 Volts

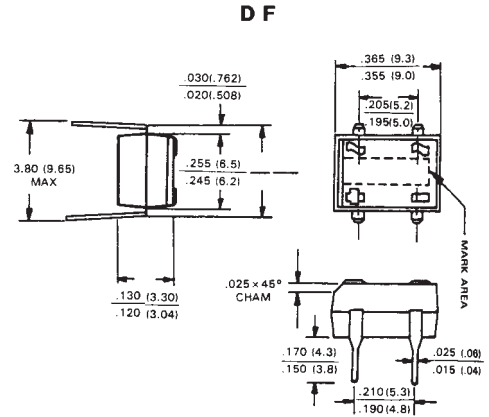
Forward Current - 1.0 Ampere

Features

- Ideal for printed circuit board
- Glass passivated chip junction
- High temperature soldering guaranteed:
260°C/10 seconds at 5 lbs tension

Mechanical Data

- **Terminals:** Plated leads, solderable per MIL-STD-202, method 208
- **Case:** Molded with UL-94Class V-0 recognized flame retardant epoxy
- **Polarity:** Polarity symbol marked on body
- **Mounting Position:** Any



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Single-phase, half-wave, 60Hz, resistive or inductive load.

Ratings at 25°C, unless otherwise stated.

For capacitive load, Derate current by 20%.

Characteristic	Symbols	DF005	DF01	DF02	DF04	DF06	DF08	DF10	Units	
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	Volts	
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	Volts	
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	Volts	
Maximum average forward rectified current at $T_A=40^\circ\text{C}$	$I_{(AV)}$	1.0							Amp	
Peak forward surge current 8.3mS single half sine-wave superimposed on rated load	I_{FSM}					50.0				Amps
Maximum forward voltage at forward current per element 1.0A	V_F					1.1				Volts
I^2t -rating for fusion ($t < 8.3\text{mS}$)	I^2t					10.0				A ² S
Maximum DC reverse current at rated DC blocking voltage	I_R					10.0 500.0				μA
Typical junction capacitance (Note 1)	C_J					25.0				pF
Typical thermal resistance (Note 2)	$R_{\theta(JA)}$					40.0				°C/W
Operating temperature range	T_J					-55 to +125				°C
Storage temperature range	T_{STG}					-55 to +150				°C

Notes:

(1) Measured at 1.0MHz and applied reverse voltage of 4.0 VDC

(2) Thermal resistance from junction to ambient on P.C. Board Mounted

RATINGS AND CHARACTERISTIC CURVES

